	DG30N60	版本号: V1.0
	绝缘栅双极型晶体管	

## 产品概述

IGBT既有功率MOSFET输入阻抗高, 控制功率小, 易于驱动, 控制简单的特点, 又有双极晶体管的导通电压低, 通态电流大, 损耗小的显著优点。在提倡节能减排、低碳经济的时代, 具备节能效率高, 便于规模化生产等优点的IGBT已成为功率半导体市场发展的主流技术。

## 产品特点

- 采用NPT技术
- 高开关速度:  $t_f = 130\text{ns}$
- 低饱和压降:  $V_{CE(sat)} = 1.3\text{V} @ I_c=30\text{A}$
- 高输入阻抗
- 热稳定性好

## 应用领域

主要用于电焊机。

## 特征参数

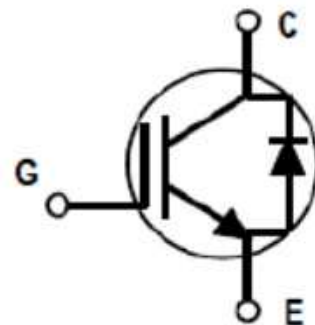
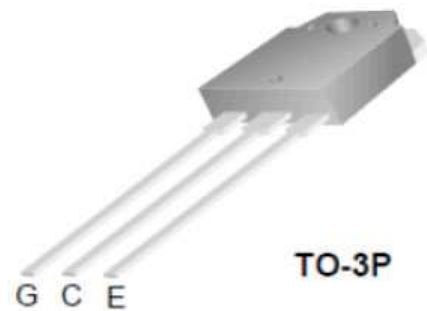
符号	额定值	单位
$V_{(BR)CES}$	600	V
$I_c$	30	A
$V_{CE(sat)}$	2.2	V

## 极限值

除非另有规定,  $T_a=25^\circ\text{C}$

参数名称	符号	额定值	单位
集电极-发射极击穿电压	$V_{CE}$	600	V
连续集电极	$I_c$	30	A
脉冲集电极电流	$I_{cpuls}$	100	A
栅-发射极电压	$V_{GE}$	$\pm 30$	V
耗散功率 $T_c=25^\circ\text{C}$	$P_D$	280	W
工作温度范围	$T_J$	-55 to +150	$^\circ\text{C}$
贮存温度范围	$T_{STG}$	-55 to +150	$^\circ\text{C}$

封装: TO-3P

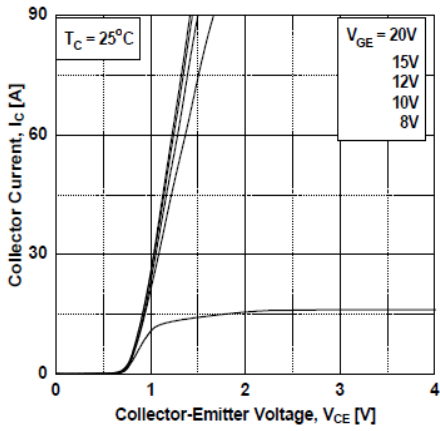


## 电参数

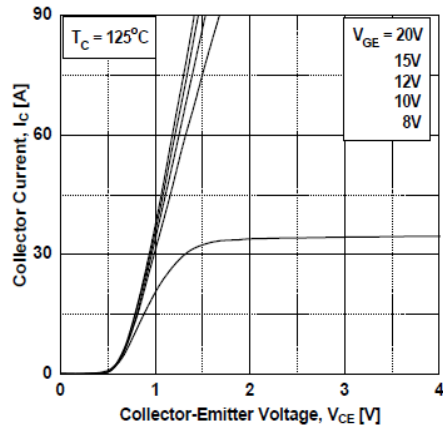
除非另有规定,  $T_a=25^{\circ}\text{C}$

参数名称	符号	测试条件	规范值			单位
			最小	典型	最大	
$V_{(BR)CES}$	集电极-发射极击穿电压	$V_{GE}=0$ $I_C=250\mu\text{A}$	600			V
$I_{CES}$	集电极-发射极泄漏电流	$V_{GE}=0$ $V_{CE}=600\text{V}$			280	$\mu\text{A}$
$I_{GSS}$	栅极-发射极泄漏电流	$V_{CE}=0$ $V_{GE}=20\text{V}$			300	nA
$V_{GE(th)}$	开启电压	$V_{GE}=V_{CE}$ , $I_D=250\mu\text{A}$	3.0		6.0	V
$V_{CE(sat)}$	集电极-发射极饱和压降	$V_{GE}=15\text{V}$ , $I_C=30\text{A}$		2.2	2.5	V
$g_{fs}$	跨导	$V_{CE}=40\text{V}$ , $I_C=15\text{A}$		11		S
$C_{iss}$	输入电容	$V_{CE}=30\text{V}$ , $V_{GE}=0$ , $f=1\text{MHz}$		2000		pF
$C_{oss}$	输出电容			200		pF
$C_{rss}$	反向恢复电容			65		pF
$Q_g$	栅电荷	$V_{CC}=400\text{V}$ $I_C=30\text{A}$ $V_{GE}=15\text{V}$		125	175	nC
$t_{d(on)}$	导通延时	$V_{CC}=400\text{V}$ , $I_C=30\text{A}$ , $R_G=10\ \Omega$ 感性负载		33		ns
$t_r$	上升时间			45		ns
$t_{d(off)}$	关断延时			123		ns
$t_f$	下降时间			105		ns
$E_{on}$	开启能量			0.53		mJ
$E_{off}$	关断能量			1.84		mJ
$t_{d(on)}$	导通延时	$V_{CC}=400\text{V}$ , $I_C=30\text{A}$ , $R_G=10\ \Omega$ $T_C=150^{\circ}\text{C}$ 感性负载		31		ns
$t_r$	上升时间			46		ns
$t_{d(off)}$	关断延时			131		ns
$t_f$	下降时间			115		ns
$E_{on}$	开启能量			0.68		mJ
$E_{off}$	关断能量			2.05		mJ
$V_{FM}$	二极管正向压降	$I_F=20\text{A}$		1.9	2.7	V
$t_{rr}$	二极管反向恢复时间	$I_F=20\text{A}$ $di/dt=200\text{A}/\mu\text{s}$		50		ns
$Q_{rr}$	二极管反向恢复电荷				80	nC

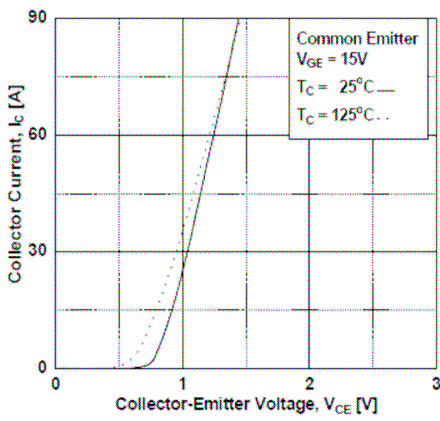
## 典型特性曲线



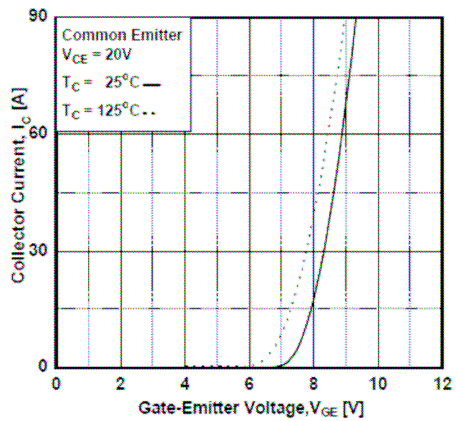
典型输出特性曲线 (T=25°C)



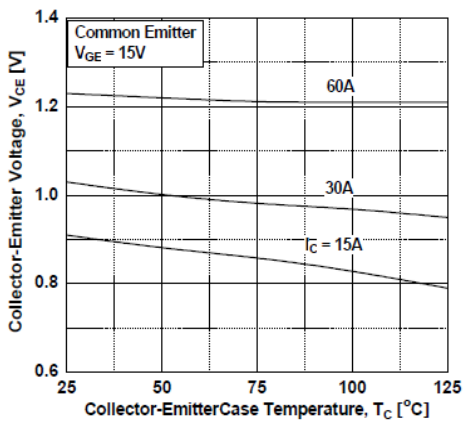
典型输出特性曲线 (T=125°C)



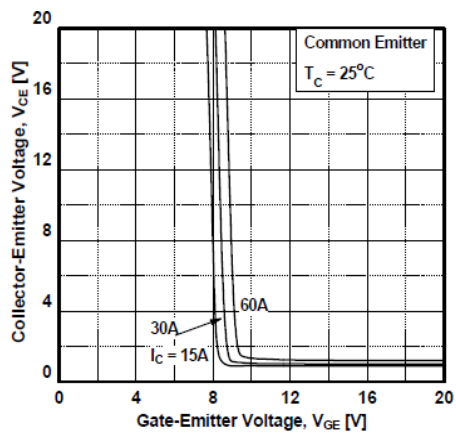
饱和和压降特性曲线



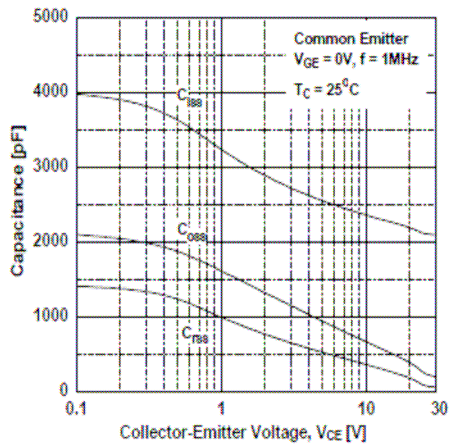
转移特性曲线



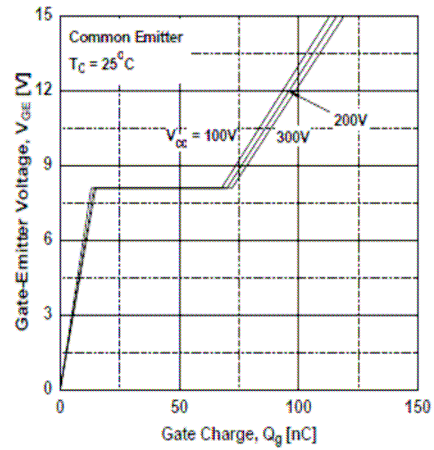
集电极-发射极饱和压降与管壳温度的关系曲线



集电极-发射极饱和压降与 V<sub>GE</sub> 关系



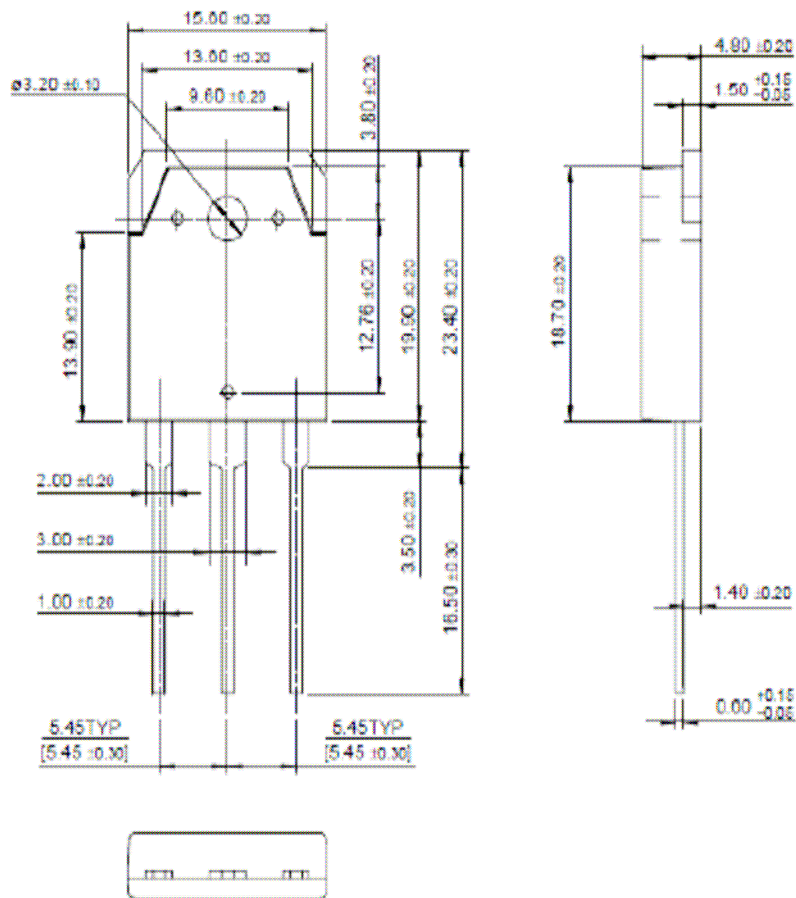
电容特性



栅电荷特性

附录：封装尺寸

TO-3P



 <b>D. G. M. E.</b>	DG30N60	Version No. : V1.0
	IGBT	

### General Description

IGBT has been the major switching device in power electronic applications as it has the merits of both power bipolar and power MOSFET. It has been widely used in high voltage field, which ranges from industrial areas such as inverters, high voltage switch, and motor operation to PDP or home appliance.

### Features

- Employing NPT technology
- High speed switching:  $t_f = 130\text{ns}$
- Low saturation voltage:  $V_{CE(sat)} = 1.3\text{V} @ I_c=30\text{A}$
- High input impedance

### Applications

Welder

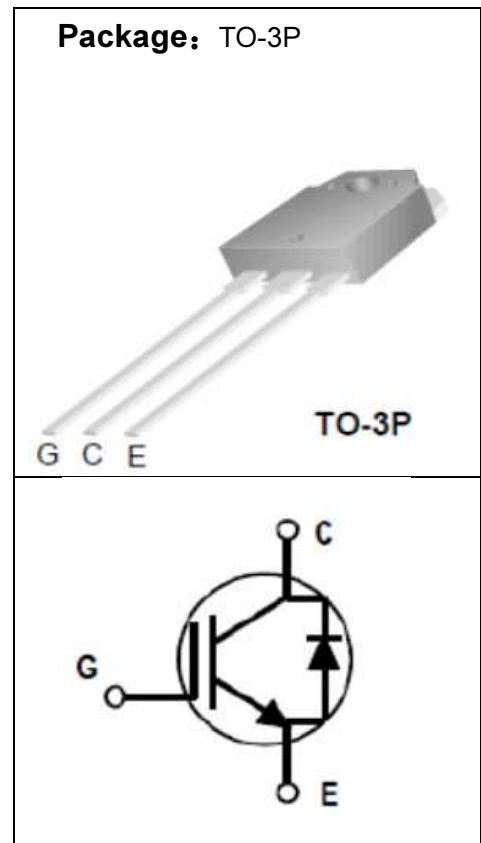
### Characteristic parameter

SYMBOL	Value	Unit
$V_{(BR)CES}$	600	V
$I_c$	30	A
$V_{CE(sat)}$	2.2	V

### Maximum Ratings

$T_c=25^\circ\text{C}$ , unless otherwise specified

PARAMETER	SYMBOL	Value	Unit
Collector-emitter voltage	$V_{CE}$	600	V
DC collector	$I_c$	30	A
Pulsed collector current	$I_{cpuls}$	100	A
Gate-emitter voltage	$V_{GE}$	$\pm 30$	V
Power dissipation $T_c=25^\circ\text{C}$	$P_D$	280	W
Operating junction temperature	$T_J$	-55 to +150	$^\circ\text{C}$
Storage temperature	$T_{STG}$	-55 to +150	$^\circ\text{C}$

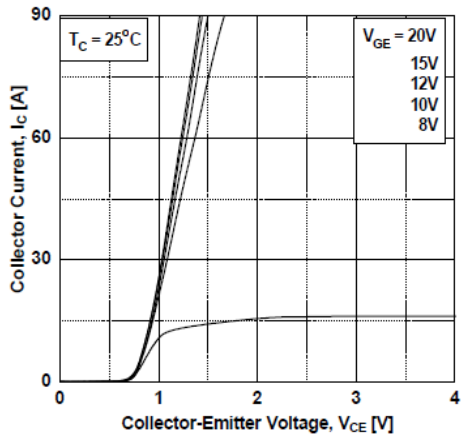


## Electrical Characteristic

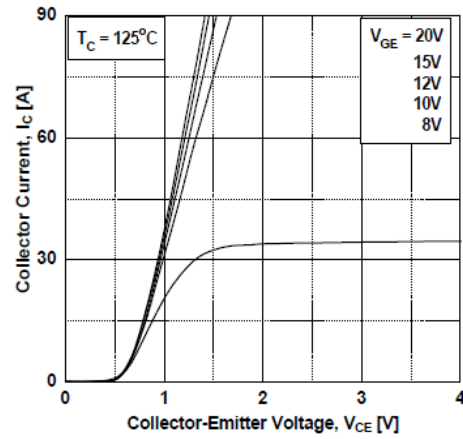
at Tc=25°C, unless otherwise specified

PARAMETER	SYMBOL	Conditions	Value			Unit
			Min.	Typ.	Max.	
V <sub>(BR)CES</sub>	Collector-emitter breakdown voltage	V <sub>GE</sub> =0 I <sub>C</sub> =250uA	600			V
I <sub>CES</sub>	Zero gate voltage collector current	V <sub>GE</sub> =0 V <sub>CE</sub> =600V			280	uA
I <sub>GSS</sub>	Gate-emitter leakage current	V <sub>CE</sub> =0 V <sub>GE</sub> =20V			300	nA
V <sub>GE(th)</sub>	Gate-emitter threshold voltage	V <sub>GE</sub> =V <sub>CE</sub> , I <sub>D</sub> =250uA	3.0		6.0	V
V <sub>CE(sat)</sub>	Collector-emitter saturation voltage	V <sub>GE</sub> =15V, I <sub>C</sub> =30A		2.2	2.5	V
C <sub>iss</sub>	Input capacitance	V <sub>CE</sub> =30V, V <sub>GE</sub> =0, f=1MHz		2000		pF
C <sub>oss</sub>	output capacitance			200		pF
C <sub>rss</sub>	Reverse transfer capacitance			65		pF
Q <sub>g</sub>	Gate charge	V <sub>CC</sub> =400V I <sub>C</sub> =30A V <sub>GE</sub> =15V		125	175	nC
td(on)	Turn-on delay time	V <sub>CC</sub> =400V, I <sub>C</sub> =30A, R <sub>G</sub> =10 Ω Inductive load		33		ns
t <sub>r</sub>	Rise time			45		ns
td(off)	Turn-off delay time			123		ns
t <sub>f</sub>	Fall time			105		ns
E <sub>on</sub>	Turn-on energy			0.53		mJ
E <sub>off</sub>	Turn-off energy			1.84		mJ
td(on)	Turn-on delay time	V <sub>CC</sub> =400V, I <sub>C</sub> =30A, R <sub>G</sub> =10Ω T <sub>C</sub> =150°C Inductive load		31		ns
t <sub>r</sub>	Rise time			46		ns
td(off)	Turn-off delay time			131		ns
t <sub>f</sub>	Fall time			115		ns
E <sub>on</sub>	Turn-on energy			0.68		mJ
E <sub>off</sub>	Turn-off energy			2.05		mJ
V <sub>FM</sub>	Diode forward voltage	I <sub>F</sub> =20A		1.9	2.7	V
t <sub>rr</sub>	Diode reverse recovery time	I <sub>F</sub> =20A di/dt=200A/ us		50		ns
Q <sub>rr</sub>	Diode reverse recovery charge				80	

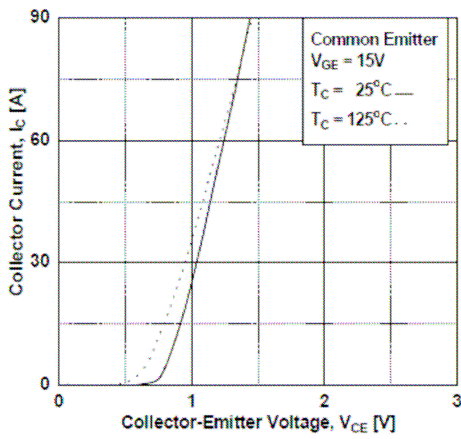
## Characteristic curves



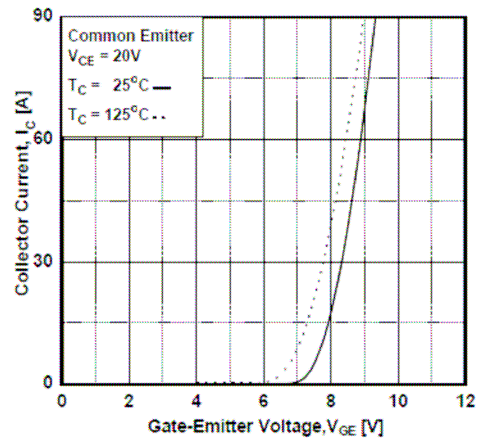
Typical output characteristic  
( $T_C=25^\circ\text{C}$ )



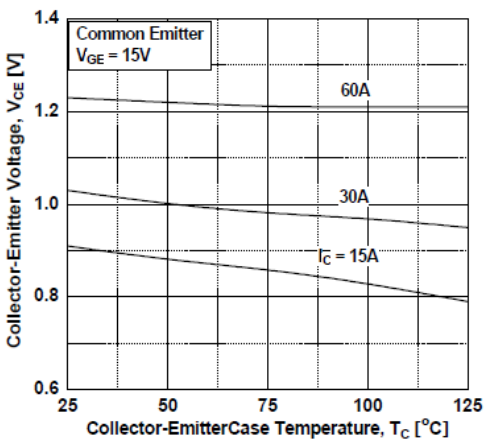
Typical output characteristic  
( $T_C=150^\circ\text{C}$ )



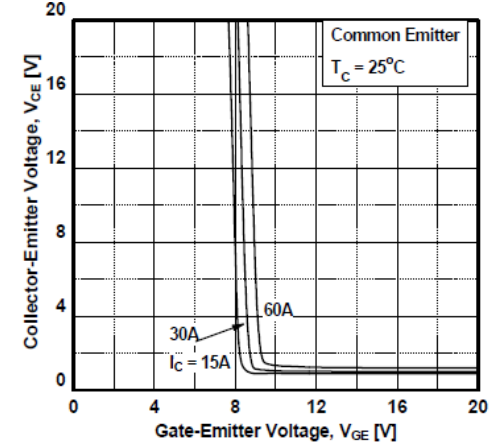
Typical collector-emitter saturation  
voltage characteristic



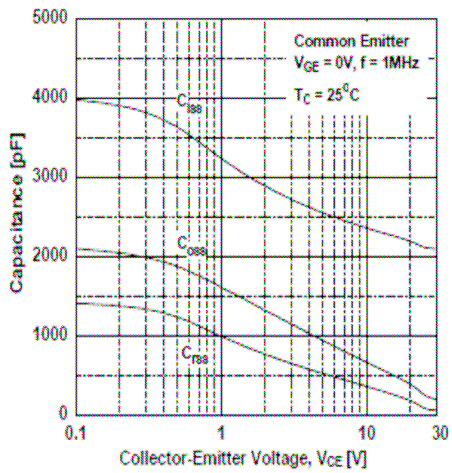
Typical transfer characteristic



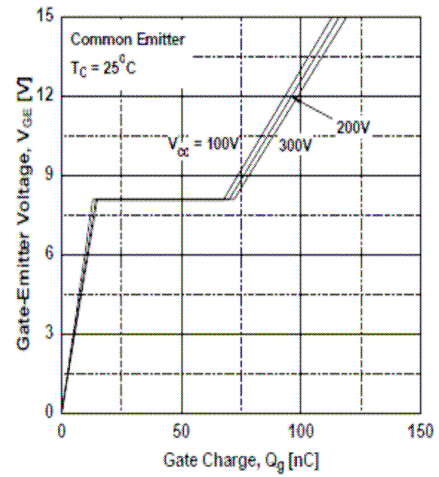
Typical collector-emitter voltage as a  
function of junction temperature



Typical collector-emitter voltage as a  
function of Gate-emitter voltage



Typical capacitance as a function of collector-emitter voltage  
 ( $V_{GE}=0V$   $f=1MHz$ )



Typical gate charge

## Package Dimension

### TO-3P

